



SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL32B106KPINFNE
- Description : CAP, 10μ F, 10V, $\pm 10\%$, X7R, 1210

A. Samsung Part Number

			<u>CL</u>	<u>32</u>	<u>B</u>	<u>106</u>	<u>K</u>	<u>P</u>	Ţ	<u>N</u>	E	<u>N</u>	E	
			1	2	3	4	(5)	6	1	8	9	10	1	
1	Series	Samsun	g Multi	-layer	Cera	amic C	apad	citor						
2	Size		(inch c	-				± 0.3		mm		W:	2.5 ± 0.2	mm
3	Dielectric	X7R					(8)	Inne	r ele	ctroc	le		Ni	
4	Capacitance	10	μF				Ŭ	Term			-		Cu	
5	Capacitance	±10	%					Plati	ng				Sn 100%	(Pb Free)
	tolerance						9	Prod	uct				Product for F	OWER application
6	Rated Voltage	10	V				10	Spec	ial				Reserved for	future use
\bigcirc	Thickness	2.0	± 0.2	mm			1	Pack	agir	ng			Embossed T	ype, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1kHz±10% 1.0±0.2Vrms						
Tan δ (DF)	0.05 max.							
Insulation	10,000Mohm or 100Mohm · <i>μ</i> F	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×10)						
Withstanding	No dielectric breakdown or	250% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	X7R							
Characterisitcs	(From -55 ℃ to 125 ℃, Capacitance change shoud be within ±15%)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (2mm)						
		with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120℃ for 10~30sec.)						
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5°C, 10±1sec.						
Soldering heat	Tan δ, IR : initial spec.							

	Performance	Test condition					
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm					
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)					
		2hours \times 3 direction (x, y, z)					
Moisture	Capacitance change : within ±12.5%	With rated voltage					
Resistance	Tan δ : 0.075 max	40±2℃, 90~95%RH, 500+12/-0hrs					
	IR : 500Mohm or 25Mohm $\cdot \mu F$						
	Whichever is Smaller						
High Temperature	Capacitance change : within ±12.5%	With 200% of the rated voltage					
Resistance	Tan δ : 0.075 max	Max. operating temperature					
	IR : 1000Mohm or 50Mohm · μF						
	Whichever is Smaller	1000+48/-0hrs					
Temperature	Capacitance change : within ±7.5%	1 cycle condition					
Cycling	Tan δ, IR : initial spec.	Min. operating temperature \rightarrow 25 °C					
		\rightarrow Max. operating temperature \rightarrow 25 °C					
		5 cycle test					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.